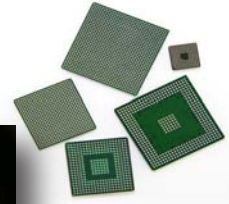
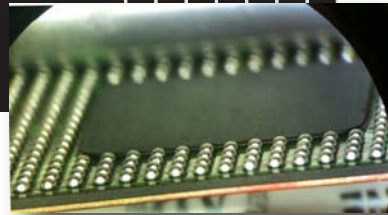


BGA BALLING SERVICES



Capabilities:

- Initial BGA & μ BGA Balling
- BGA Repair / Rework
- Substrate Sizes up to 44mm Square
- Sphere Sizes from 0.10" to 0.30"
- SnPb or Pb-Free Spheres
- Same-Day Service Available
- Clean-room Environment
- Outstanding Quality & Customer Service

With the increase in popularity of Ball Grid Array packages in many electronic applications, Quik-Pak is addressing the need for prototype BGA devices. To complement our existing assembly processes, Quik-Pak has added BGA sphere attach services.

Quik-Pak can attach spheres, in sizes ranging from 0.010" to 0.030" (0.25 to 0.76mm), to substrates as large as 44mm square. This balling service is applicable to new laminate or ceramic substrates or for rework of existing packages.

Quik-Pak offers spheres in the following SnPb and Pb-free alloys:

- 63 Sn / 37 Pb
- 96.5 Sn / 3.5 Ag
- 96.5 Sn / 3.0 Ag / 0.5Cu

BGA balling is offered as an individual service, or can be combined with Quik-Pak's other assembly services.

Quik-Turn Service

When you need to meet a project or customer deadline, you can count on Quik-Pak's reliable on-time delivery options - including same-day expedited service. In fact, we can receive a wafer in the morning and ship completely assembled BGA devices by the end of the day.

When you require a full turn-key provider of production-quality prototype parts for internal testing or customer samples, Quik-Pak is the answer. Services include Wafer Backgrinding & Dicing, Package Procurement and Open Cavity Preparation, Die Attach, Wire Bonding, Encapsulation, Remolding and Marking.

Quik-Pak

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